

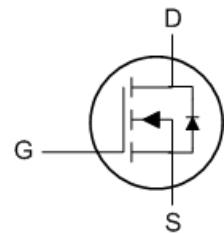
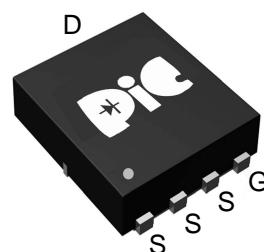
➤ General Description

This PAN00SY94AY N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and GreenProduct requirement with full function reliability approved

➤ Feature

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

➤ **DFN5X6A-EP1**



➤ Application

- DC/DC Primary Side Switch
- Industrial Synchronous
- Rectification Load Switch
- DC/DC Converters

➤ Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current ¹	I _D @T _c =25°C	60	A
Continuous Drain Current ¹	I _D @T _c =100°C	39	A
Pulsed Drain Current ²	I _{DM}	160	A
Single Pulse Avalanche Energy ³	EAS	33	mJ
Avalanche Current	I _{AS}	15	A
Total Power Dissipation ⁴	P _D @T _c =25°C	56.5	W
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 150	°C
Thermal Resistance Junction-Ambient ¹	R _{θJA}	50	°C/W
Thermal Resistance Junction-Case ¹	R _{θJC}	2.2	°C/W

➤ **Electrical Characteristics (T_J=25°C Unless otherwise noted)**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V , I _D =250uA	100	---	---	V
Static Drain-Source On-Resistance ²	R _{DS(ON)}	V _{GS} =10V , I _D =20A	---	8	11.5	mΩ
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250uA	2	---	4	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =80V , V _{GS} =0V , T _J =25°C	---	---	1	uA
		V _{DS} =80V , V _{GS} =0V , T _J =55°C	---	---	5	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
Total Gate Charge (10V)	Q _g	V _{DS} =50V , V _{GS} =10V , I _D =20A	---	26	---	nC
Total Gate Charge (4.5V)	Q _g		---	12	---	
Gate-Source Charge	Q _{gs}		---	5.5	---	
Gate-Drain Charge	Q _{gd}		---	5	---	
Turn-On Delay Time	T _{d(on)}	V _{DD} =50V , V _{GS} =10V , R _G =3.3Ω, I _D =20A	---	7.6	---	ns
Rise Time	T _r		---	3.8	---	
Turn-Off Delay Time	T _{d(off)}		---	26	---	
Fall Time	T _f		---	5.8	---	
Input Capacitance	C _{iss}	V _{DS} =50V , V _{GS} =0V , f=1MHz	---	2422	---	pF
Output Capacitance	C _{oss}		---	288	---	
Reverse Transfer Capacitance	C _{rss}		---	12	---	

➤ **Diode Characteristics**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current ^{1,5}	I _s	V _G =V _D =0V , Force Current	---	---	35	A
Diode Forward Voltage ²	V _{SD}	V _{GS} =0V , I _s =1A , T _J =25°C	---	---	1.2	V
Reverse Recovery Time	t _{rr}	I _F =20A , di/dt=100A/μs , T _J =25°C	---	40	---	nS
Reverse Recovery Charge	Q _{rr}		---	162	---	nC

Note :

- 1.Pulse width limited by maximum junction temperature.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.3mH,I_{AS}=15A
- 4.Ensure that the channel temperature does not exceed 150°C.
- 5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

➤ Typical Characteristics

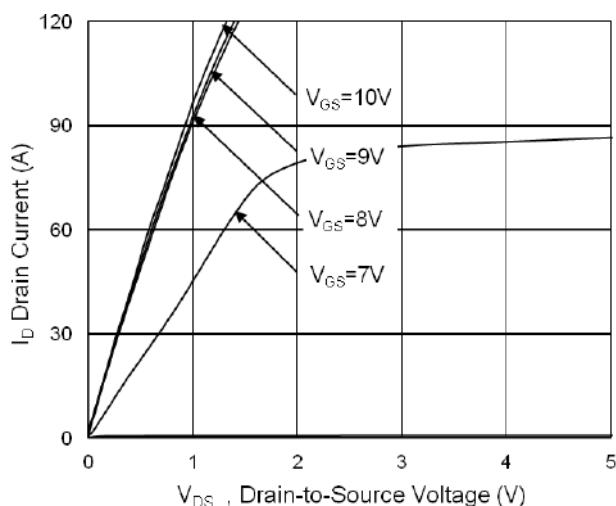


Fig.1 Typical Output Characteristics

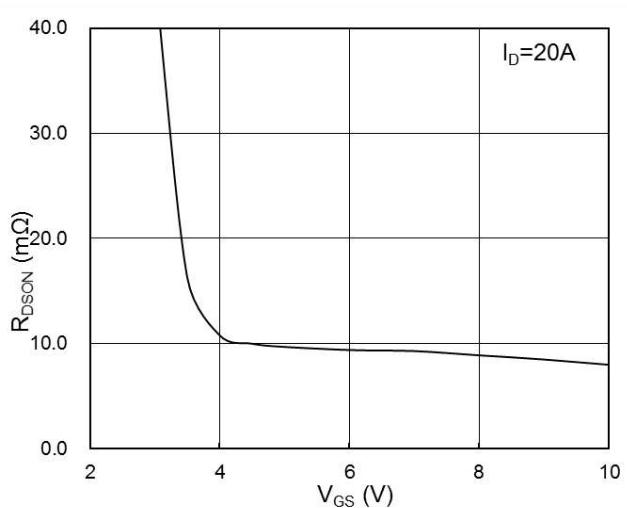


Fig.2 On-Resistance vs G-S Voltage

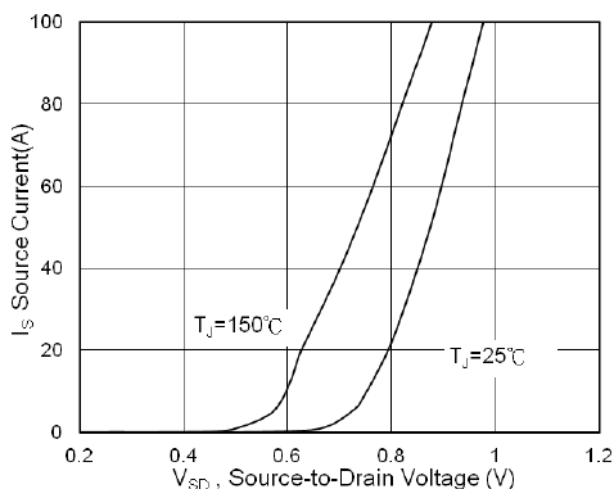


Fig.3 Source Drain Forward Characteristics

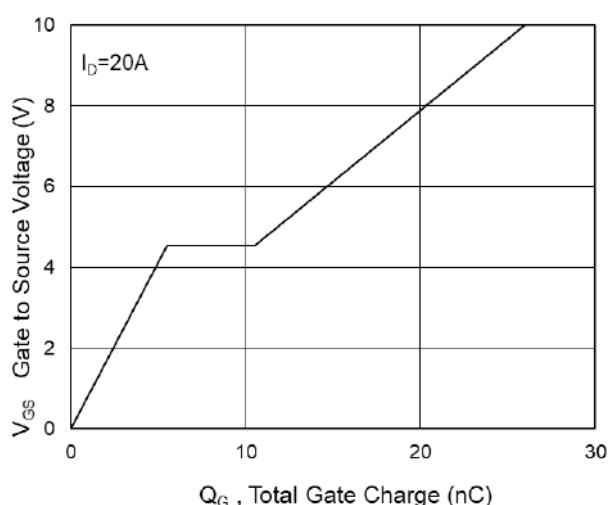


Fig.4 Gate-Charge Characteristics

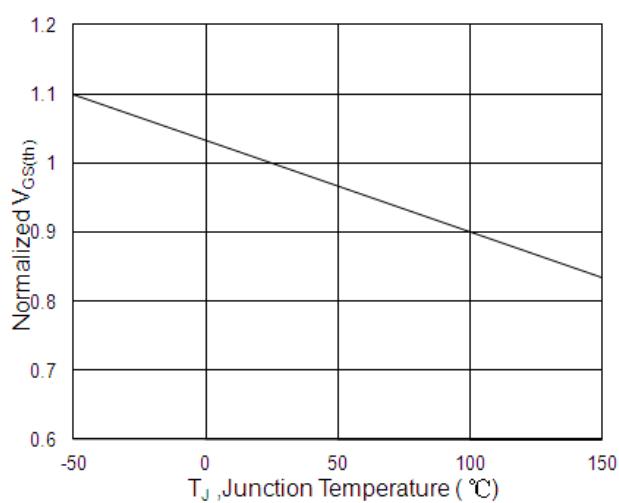


Fig.5 Normalized $V_{GS(th)}$ vs T_J

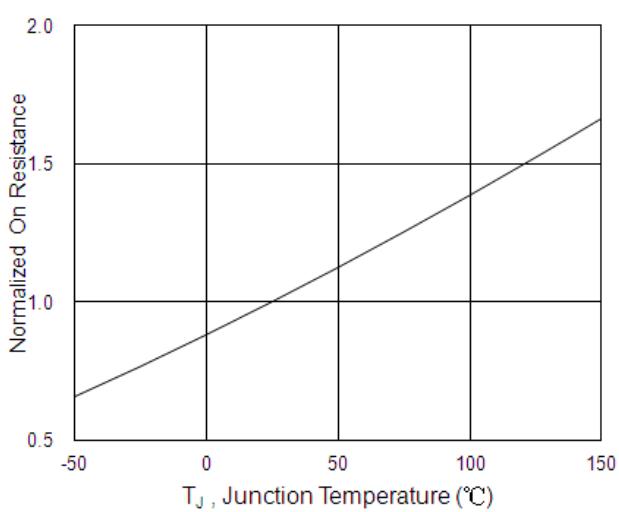
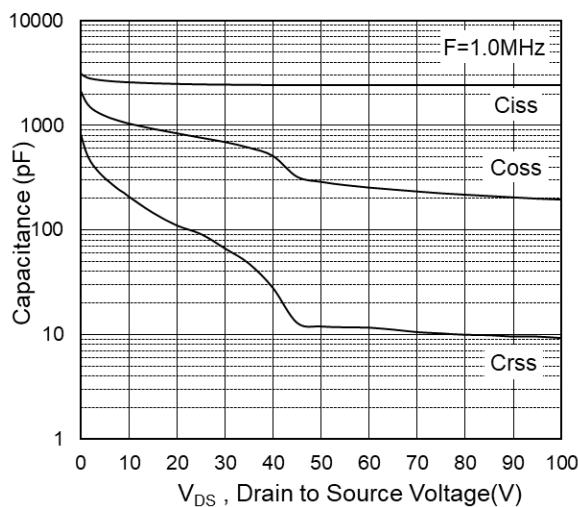
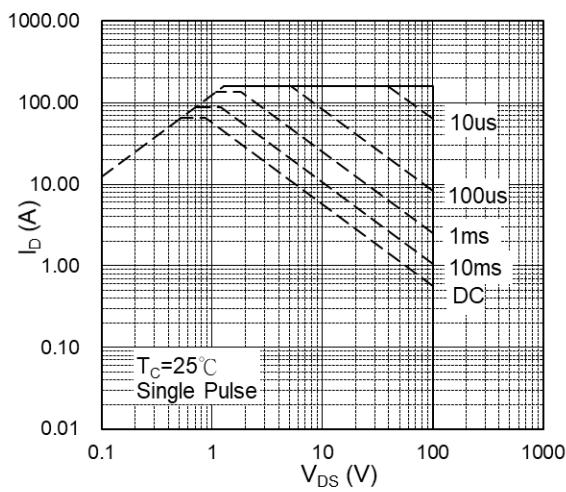
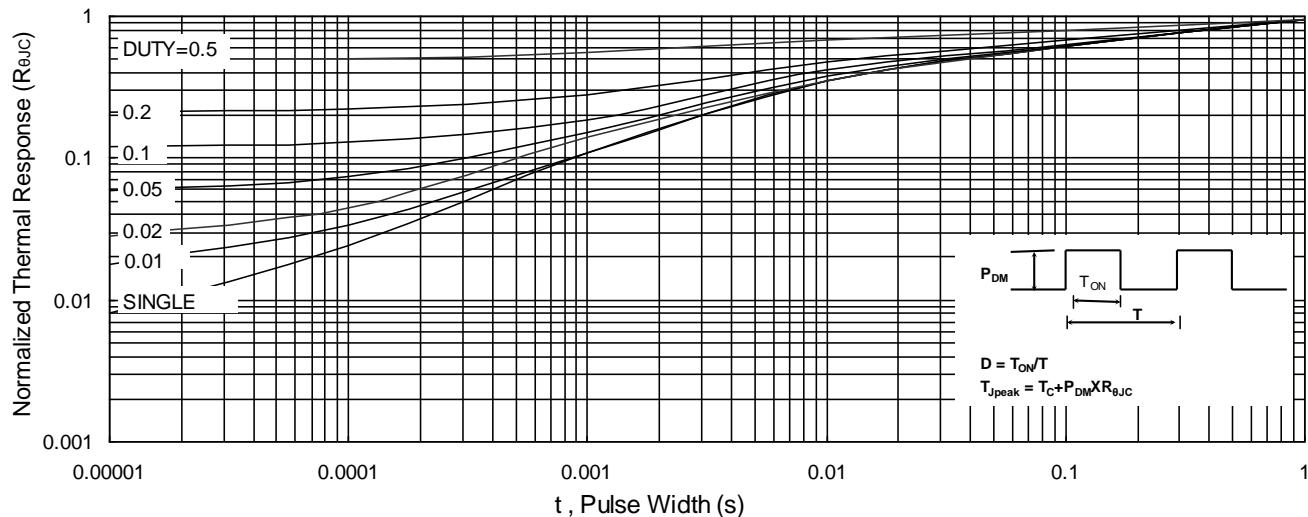
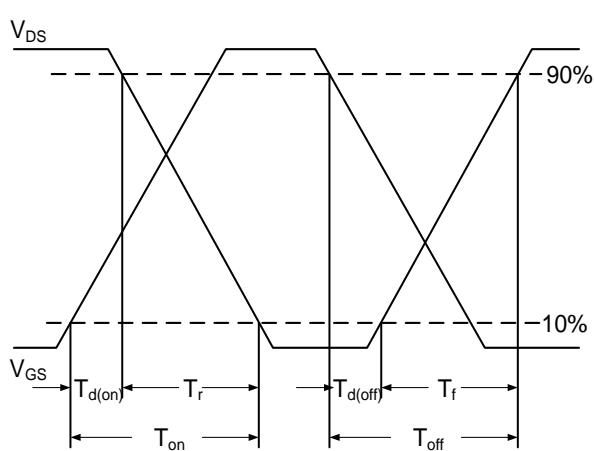
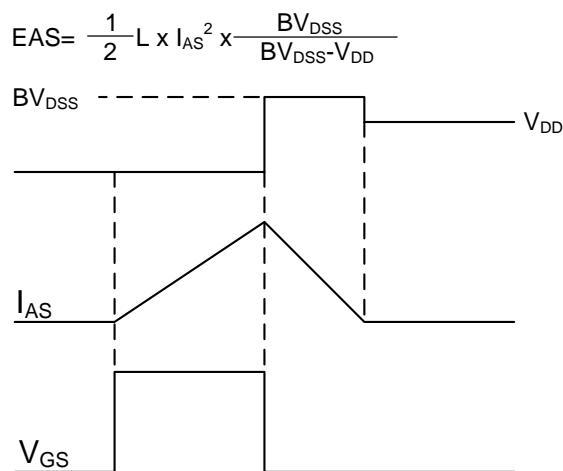
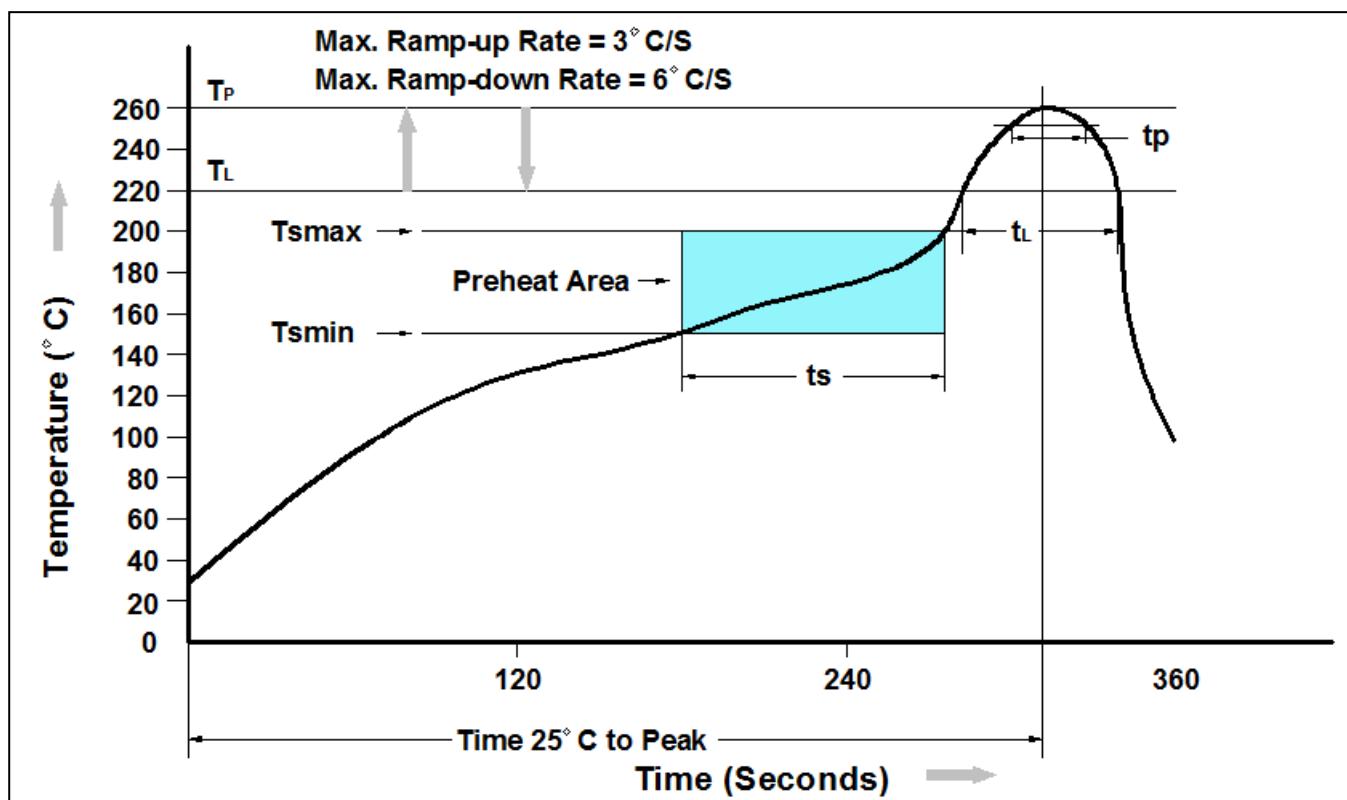


Fig.6 Normalized $R_{DS(on)}$ vs T_J

N-Ch 100V Fast Switching MOSFET
V_{DS}=100V, I_D=60A, R_{DSON}=11.5mΩ

Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform

➤ **Recommand IR Reflow Soldering Thermal Profile**

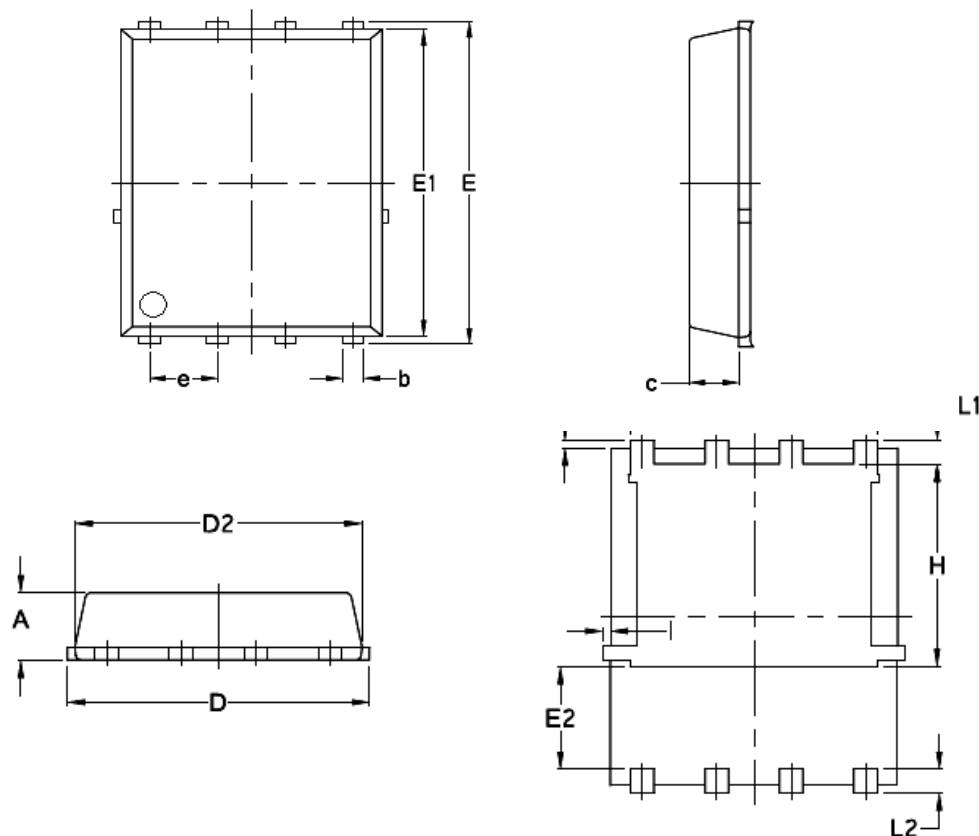


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	150°C
Temperature Max. (T _{smax})	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds
Average Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

➤ **Ordering Information**

Part Number	Description	Quantity
PAN00SY94AY	DFN5X6A-EP1	3000 pcs

➤ **Package Information (DFN5X6A-EP1)**



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.970	0.0324	0.0382
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
I	---	0.18	---	0.0070
E	5.90	6.15	0.2323	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.10	---	0.0433	---
e	1.27 BSC		0.05 BSC	
H	3.30	3.78	0.1299	0.1488
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.61	0.0150	0.0240
L2	0.38	0.71	0.0150	0.0279

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